











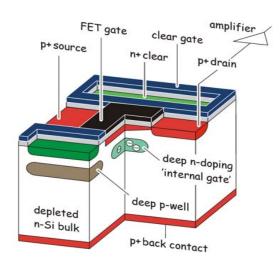


The DEPFET-PXD-Project: Towards a Pixel Vertex Detector @ Belle-II





C. Kiesling, Max-Planck-Institute for Physics, Munich (for the DEPFET-Collaboration)



- Organizational Matters
- News from the German Funding Agencies
- Work Packages Update
- Timeline
- Conclusions & Outlook

DEPFET-Collab. @ Belle-II

Original Collaboration: DEPFET pixel detector @ ILC (since 2002) now: Unite efforts to deliver a REAL PXD by 2013 for Belle-II

University of Barcelona, Spain Universitat Ramon Llull, Barcelona, Spain Bonn University, Germany Heidelberg University, Germany Giessen University, Germany Goettingen University, Germany Karlsruhe University, Germany IFJ PAN, Krakow, Poland MPI Munich, Germany Charles University, Prague, Czech Republic IGFAE, Santiago de Compostela University, Spain IFIC, CSIC-UVEG, Valencia, Spain

with important help from Hawaii, KEK, Vienna

DEPFET@Belle-II

New management:

• IB- Board

- Project LeaderC. Kiesling
- Technical Coord.
 H.-G. Moser
- "Integration Coord."(Liaison @ KEK)

Institutes and Group Leaders (IB)

Czech Rep.	PRA	Charles-University Prague	Zdenek Dolezal
Germany	BON GIE GOE HEI KAR MPI	University of Bonn University of Gießen University of Göttingen University of Heidelberg University of Karlsruhe Max-Planck-Institute for Physics, Munich Semiconductor Laboratory (HLL)	Norbert Wermes Sören Lange Ariane Frey Peter Fischer Thomas Müller Christian Kiesling Hans-Günther Moser
Poland	KRA	Institute of Nuclear Physics, Krakow	Henryk Palka
Spain	IFV URL UBA CNM IFB USC IFC	Instituto de Fisica Corpuscular (IFIC), Valencia University Ramon Llull, Barcelona University of Barcelona Centro Nacional de Microelectronica, Barcelona Instituto de Fisica d'Altes Energies (IFAE), Barcelona University of Santiago de Compostela Instituto de Fiisica de Cantabria (IFCA), Santander	Carlos Lacasta Jordi Riera Babures Lluis Garrido Enric Cabruja Mokhtar Chmeissani Pablo Vazquez Regueiro Ivan Vila Alvarez
Austria	VIE	Institute for High Energy Physics (HEPHY), Vienna	Markus Friedl
Japan	KEK	KEK	Toru Tsuboyama
USA	HAW	University of Hawaii	Gary Varner

C. Kiesling, 3rd Open Meeting of the Belle-II Collaboration, KEK, July 7-9, 2009

Funding of the DEPFET-Collab.

Model: The DEPFET-Collaboration will deliver the PXD hardware and ensure the operation of the detector at Belle-II

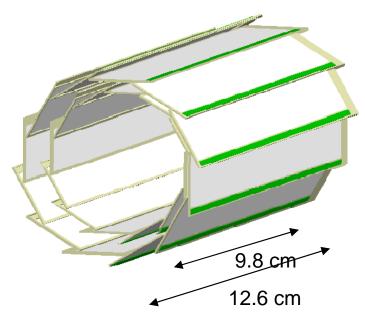
Total cost of deliverables (core cost): 2.5 M€

Funding will be provided by the DEPFET-Collaboration

The German groups have applied for Belle-II funding to the Government in December of 2008 (for the years 2009-2012):

- Asked for total of 2.17 M€ + 13.5 FTE
 (includes travel, MPI will contribute another 1 M€)
- Very positive evaluation by the Ministery
 Granted funds: 1.05 M€ + 3.5 FTE (48% of requested sum)
- New application possible after approval of SuperKEKB + MoU

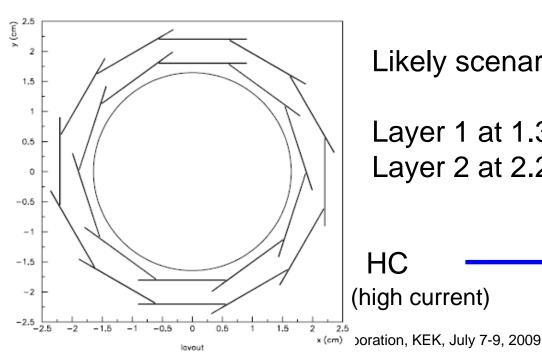
DEPFET Pixel Detector @ Belle-II



Small, thin (50µm) Detector: 2 layers, 20 modules (in total)

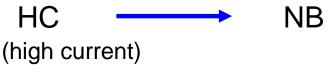
Beam pipe radius (presently): 1.0 cm in the nanobeam option (NB)

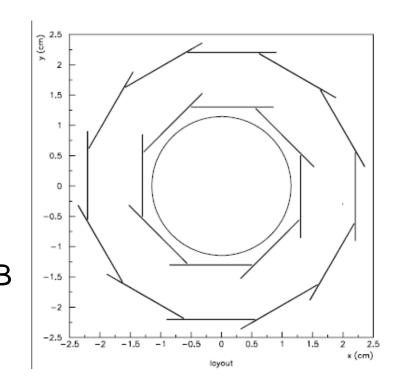
Radii still subject to optimisation:



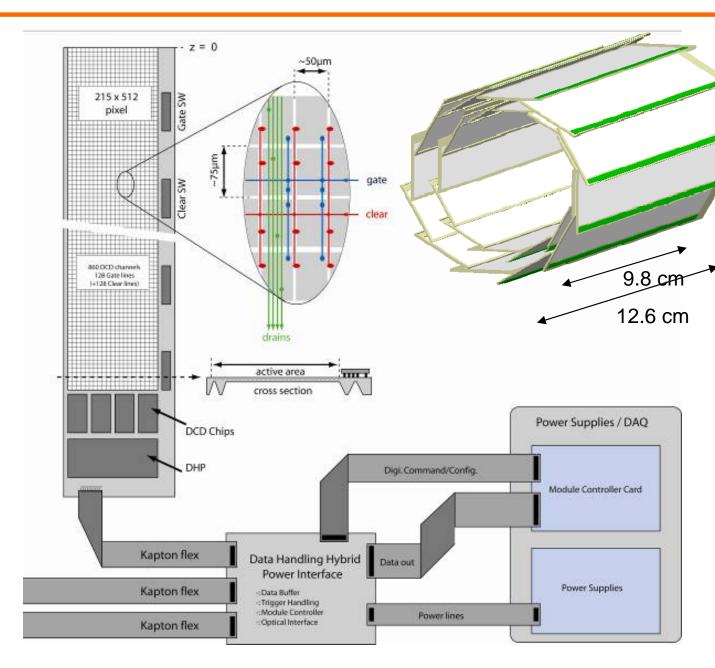
Likely scenario now:

Layer 1 at 1.3 cm Layer 2 at 2.2 cm





Main Components of the PXD



Mechanics
Power
Services
Cooling
Assembly
Control ...

Sensors
ASICs
Interconnections
Assembly
Data links
DAQ

Work Packages and Assignments

Nr.	Work Package	Lead Institution	Collab. Institutions
1.0	DEPFET Modules		
1.1	Parameter Definitions	MPI	KRA, PRA
1.2	Sensor Development	MPI	
1.3	ASIC Development		
1.3.1	Switcher	HEI	
1.3.2	DCD		
1.3.3	Data Handling Processor (DHP)	BON	MPI, UBA
1.3.4	Data link		USC, URL
1.4	Module Design		
1.4.1	Sensor Ladder	MPI	HEI, BON, IFV,
			CNM, IFB
1.4.2	Kapton Flex	KEK	VIE, BON
1.4.3	Data Handling Hybrid (DHH)	KEK	VIE, BON

Work Packages and Assignments (cont.)

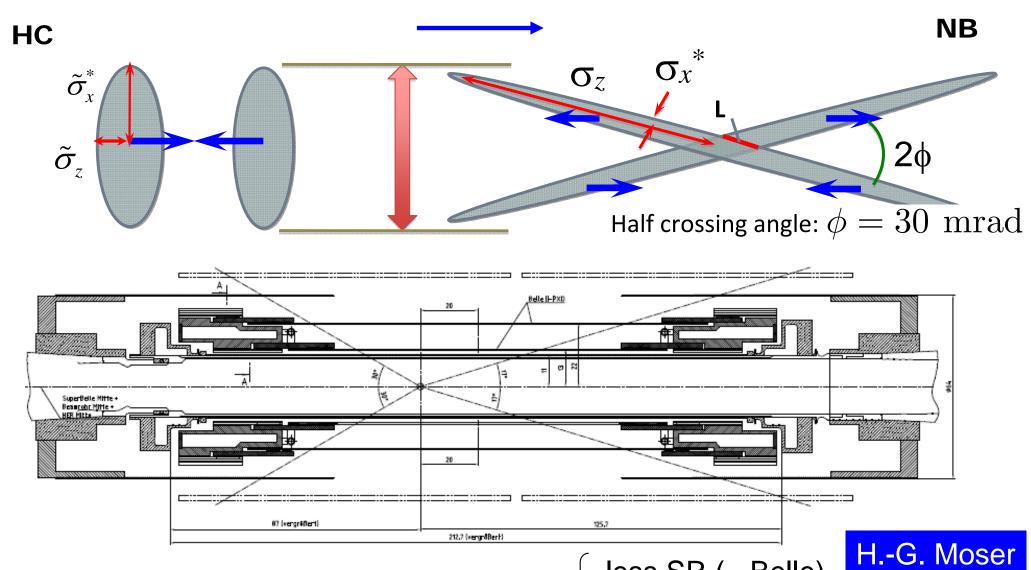
Nr.	Work Package	Lead Institution	Collab. Institutions
1.5	Mechanical Design	MPI	KAR, HAW, VIE; KRA, IFV, KEK
1.6	Thermal Issues	KAR	MPI, VIE, KRA, IFV, IFB
1.7	System		
1.7.1	Data Acqusition (pre-event builder)	GIE	KRA, GOE, MPI, KEK, URL, HAW
1.7.2	Power supplies with slow control	KRA	KEK, USC
1.7.3	Cooling plant (refigerator, heat exchanger)	KEK	

Work Packages and Assignments (cont.)

Nr.	Work Package	Lead Institution	Collab. Institutions
2.0	Test Facilities		
2.1	Test beams	PRA	KAR, BON, VIE, IFV, IFC URL,CNM, IFB, USC
2.2 2.3	Setups for thermal tests Mechanical mockup	KAR	MPI, VIE, IFV, USC, IFC
3.0	Integration and running-in scenario		
4.0	Operation Issues		

- meetings of the WP partners on demand
 Regular collaboration meetings (~ 2-3 times per year)
- Last "big" Collaboration meeting: Ringberg Castle, May 4-6, 2009
 4 Colleagues from Japan: preference for NanoBeam Scheme

NanoBeam Option



NB: so far only "good points" for the PXD:

less SR (~ Belle)
smaller beam pipe (BP)
BP parallel to Belle-II solenoid

Main R&D Issues currently

Sensors:

K. Prothmann Z. Drasal

pixel geometry -> parameter studies prototyping, radiation hardness (> 10Mrad), thinning, interconnection with ASICs

Read-out ASICs:

H.-G. Moser

Current Digitizer chip (DCD):

prototype OK, needs test at full speed (x2)

Switcher:

rad-hard design, speed OK, redesign for Belle-II

DHP & DHH:

Zero-suppr: 400 Gpx/s -> 3 Gpx/s (triggered)

-> 2.5 Gb/s per half module

DAQ:

100 Gb/s total -> Gießen ATCA system

K. Prothmann, S. Lange

Mechanics:

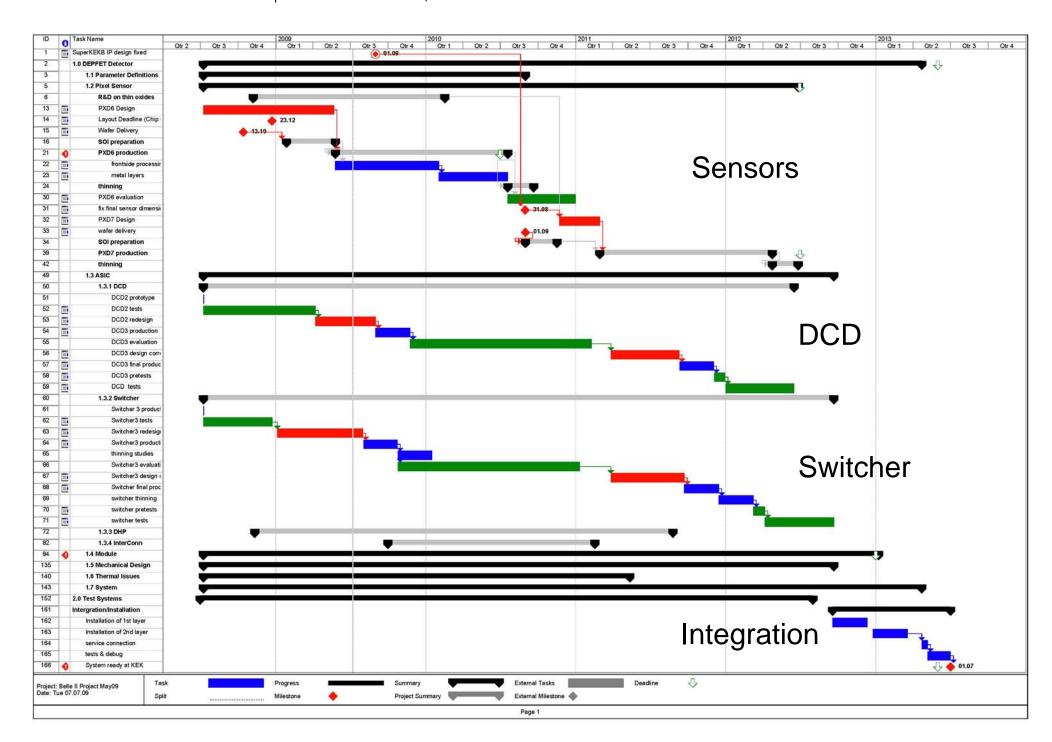
Mounting structure, cooling, alignment ...,

F. Simon

T. Müller

A. Moll

Timeline | 2009 | 2010 | 2011 | 2012 | 2013



Conclusions and Outlook

- DEPFET Collaboration stands firmly behind the PXD project for Belle-II
- Belle-II PXD group has decided on DEPFET as baseline
- Management structure of the DEPFET Collaboration @ Belle-II created
- Work packages are defined, lead institutions (+contacts) are identified
- Timeline for the project is established and agreed (but tight!)
- Working Groups have entered stage of detailed work for Belle-II PXD
- German funding agencies have approved about 50% of the core cost signals for further funding when SuperKEKB is approved
- Progress of workpackages needs now close monitoring and possibly some rework
- Next big step: TDR by spring 2010